



# Material Composition Declaration

© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

|            |  |                           |  |
|------------|--|---------------------------|--|
| 1752-2 1.1 | IPC Web Site for Information on IPC-1752 Standard<br><a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a> | Form Type *<br>Distribute | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat |
|------------|--|---------------------------|--|

## Supplier Information

|   |   |   |   |   |                    |            |     |           |
|---|---|---|---|---|--------------------|------------|-----|-----------|
| Company Name *<br>Mindspeed Technologies, Inc | Company Unique ID                                 | Unique ID Authority                         | Response Date *<br>2011-05-04                       | Response Document ID                                |                    |            |     |           |
| Contact Name *<br>Cynthia Ong                 | Title - Contact<br>Program Manager                | Phone - Contact *<br>949-579-5515           | Email - Contact *<br>cynthia.ong@mindspeed.com      |   |                    |            |     |           |
| Authorized Representative *<br>CH Choong      | Title - Representative<br>Senior Quality Engineer | Phone - Representative *<br>+6(04)-632 8036 | Email - Representative *<br>ch.choong@mindspeed.com | Supplier Comments or URL for Additional Information |                    |            |     |           |
| Requester Item Number                         | Mfr Item Number                                   | Mfr Item Name                               | Effective Date                                      | Version   | Manufacturing Site | Weight *   | UOM | Unit Type |
| M21170G-12                                    | M21170G-12  | 50 HFCBGA 2389                              |   | B   | ASE, Taiwan        | 28,375.137 | mg  | EACH      |
| Alternate Recommendation                      |   | NA  |   | Alternate Item Comments                             | NA                 |            |     |           |

## Manufacturing Process Information

|  |                     |                      |                               |                              |                         |
|--|---------------------|----------------------|-------------------------------|------------------------------|-------------------------|
| Terminal Plating / Grid Array Material | Terminal Base Alloy | J-STD-020 MSL Rating | Peak Process Body Temperature | Max Time at Peak Temperature | Number of Reflow Cycles |
| SAC                                    | N/A                 | 4                    | 245 C                         | 40 seconds                   | 3                       |
| Comments<br>NA                         |                     |                      |                               |                              |                         |

Save the fields in this form to a file

Export Data

Import fields from a file into this form

Import Data

Locked

## RoHS Material Composition Declaration

Declaration Type \*

Simplified

RoHS Directive  
2002/95/EC

**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration \*

4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions

Supplier Acceptance \*

Accepted

**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version

EL-2006/690/EC

15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

## Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Homogeneous Material Composition Declaration for Electronic Products

**SubItem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

**Line Functions:** +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

| Item/SubItem Name | Homogeneous Material | Weight   | Unit of Measure | Level | Substance Category   | Substance               | CAS          | Exempt | Weight    | Unit of Measure | Tolerance |   | PPM     |
|-------------------|----------------------|----------|-----------------|-------|----------------------|-------------------------|--------------|--------|-----------|-----------------|-----------|---|---------|
|                   |                      |          |                 |       |                      |                         |              |        |           |                 | -         | + |         |
| M21170G-12        | Substrate            | 5,376.45 | mg              | C     | GROUP-C              | Alumina                 | 1344-28-1    |        | 214.735   | mg              |           |   | 39,939  |
|                   |                      |          |                 | C     | GROUP-C              | Copper                  | 7440-50-8    |        | 2,576.285 | mg              |           |   | 479,17  |
|                   |                      |          |                 | C     | GROUP-C              | Silica                  | 7631-86-9    |        | 797.657   | mg              |           |   | 148,36  |
|                   |                      |          |                 | C     | GROUP-C              | Plyphenylene ether (PPE |              |        | 866.474   | mg              |           |   | 161,16  |
|                   |                      |          |                 | B     | Bismuth/Bismuth Com  | Bismuth                 | 7440-69-9    |        | 10.641    | mg              |           |   | 375.01  |
|                   |                      |          |                 | B     | Antimony/Antimony C  | Antimony trioxide       | 1309-64-4    |        | 50.23     | mg              |           |   | 1,770.2 |
|                   |                      |          |                 | C     | GROUP-C              | Magnesium oxide         | 1309-48-4    |        | 85.894    | mg              |           |   | 15,975  |
|                   |                      |          |                 | C     | GROUP-C              | Silver                  | 7440-22-4    |        | 4.751     | mg              |           |   | 883.66  |
|                   |                      |          |                 | C     | GROUP-C              | Calcium oxide           | 1305-78-8    |        | 343.576   | mg              |           |   | 63,903  |
|                   |                      |          |                 | B     | Arsenic/Arsenic Comp | Arsenic                 | 7440-38-2    |        | 0.235     | mg              |           |   | 8.2818  |
|                   |                      |          |                 | C     | GROUP-C              | Epoxy resin             |              |        | 105.012   | mg              |           |   | 19,531  |
|                   |                      |          |                 | C     | GROUP-C              | Talc                    | 14807-96-6   |        | 21.04     | mg              |           |   | 3,913.3 |
|                   |                      |          |                 | C     | GROUP-C              | Brome compounds         |              |        | 163.249   | mg              |           |   | 30,363  |
|                   |                      |          |                 | C     | GROUP-C              | Tin                     | 7440-31-5    |        | 112.497   | mg              |           |   | 20,924  |
|                   |                      |          |                 | C     | GROUP-C              | Barium sulfate          | 7727-43-7    |        | 24.174    | mg              |           |   | 4,496.2 |
| Heatslug          |                      | 20,103.7 | mg              | C     | GROUP-C              | Copper                  | 7440-50-8    |        | 19,983.07 | mg              |           |   | 993,99  |
|                   |                      |          |                 | B     | Nickel/Nickel Compou | Nickel                  | 7440-02-0    |        | 120.6222  | mg              |           |   | 4,250.9 |
| Solder ball       |                      | 2,105.3  | mg              | C     | GROUP-C              | Ag                      | 7440-22-4    |        | 63.159    | mg              |           |   | 30,000  |
|                   |                      |          |                 | C     | GROUP-C              | Sn                      | 7440-31-5    |        | 2,031.614 | mg              |           |   | 964,99  |
|                   |                      |          |                 | C     | GROUP-C              | Cu                      | 7440-50-8    |        | 10.5265   | mg              |           |   | 5,000   |
| Thermally condu   |                      | 280      | mg              | C     | GROUP-C              | Alumina                 | 01344-28-1   |        | 252       | mg              |           |   | 899,99  |
|                   |                      |          |                 | C     | GROUP-C              | Others                  | Trade Secret |        | 28        | mg              |           |   | 99,999  |
| Underfill         |                      | 46       | mg              | C     | GROUP-C              | Silicon dioxide         | 60676-86-0   |        | 21.16     | mg              |           |   | 459,99  |

|      |       |    |  |   |                    |  |                         |              |  |       |    |  |  |         |
|------|-------|----|--|---|--------------------|--|-------------------------|--------------|--|-------|----|--|--|---------|
|      |       |    |  | C | GROUP-C            |  | Carbon black            | 1333-86-4    |  | 0.46  | mg |  |  | 9,999.9 |
|      |       |    |  | C | GROUP-C            |  | Amine type accelerator  | Trade Secret |  | 2.3   | mg |  |  | 49,999  |
|      |       |    |  | C | GROUP-C            |  | Phenolic resin          | 9003-35-4    |  | 9.2   | mg |  |  | 199,99  |
|      |       |    |  | C | GROUP-C            |  | Bisphenol A type liquid | 25068-38-6   |  | 1.38  | mg |  |  | 29,999  |
|      |       |    |  | C | GROUP-C            |  | Bisphenol F type liquid | 9003-36-5    |  | 9.2   | mg |  |  | 199,99  |
|      |       |    |  | C | GROUP-C            |  | Additives               | Trade Secret |  | 2.3   | mg |  |  | 49,999  |
| Die  | 460.7 | mg |  | C | GROUP-C            |  | Silicon                 | 7440-21-3    |  | 460.7 | mg |  |  | 999,99  |
| Bump | 2.988 | mg |  | A | Lead/Lead Compound |  | Sn                      | 7439-92-1    |  | 0.33  | mg |  |  | 110,44  |
|      |       |    |  | C | GROUP-C            |  | Pb                      | 7440-31-5    |  | 2.658 | mg |  |  | 889,55  |